



Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 15.0001

CB Certificate No.: 026/QCA

Schedule Number: IECQ-C BSI 15.0001-S

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Page 1 of 1

Board Types:	Rigid Multilayer			BS 123300-003
	Rigid double-sided with plated through holes			BS 123200-003
	Rigid single & double-sided with plain holes			BS 123100-003
	Flex-Rigid multilayer with through holes			BS 123600-003
Base Materials:	Epoxide Woven Glass			
	Polyimide Film			
Board Size:	495.30 mm x 419.10 mm multilayer			BS 123300-003
	261.87 mm x 322.33 mm multilayer			BS 123600-003
Number of Layers	32 maximum			BS 123300-003
	10 maximum			BS 123600-003
Conductors	0.10 mm (photomech) Tolerance -0.02 mm +0.03 mm			
Plated-through Hole Diameter:	0.20 mm	Minimum	Finished hole size	BS 123300-003
	0.80 mm	Minimum	Finished hole size	BS 123600-003
Aspect Ratio:	16.4 : 1	Maximum		BS 123300-003
	2.27 : 1	Maximum		BS 123600-003
Finishes:	* Hot Air Solder Levelling			
	Immersion Silver			
	2.5µm Gold over Copper Edge Contacts			
	Liquid Photopolymer Solder Resist			
	Legend; UV or Oven Cured			
	Solder resist UV cured			
Additional:	Selective Electroplated Gold (2.5 µm) on Copper			
	Selective Electroless Gold (0.07 µm) on Nickel			

* This finish meets the Solderability requirements

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